

COMPLETE LISTING OF ALL OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-7 (Previously canceled)

Claims 8-12 (Canceled)

Claim 13 (Original): An assembled substrate, comprising
a substrate having a first side and a second side, and
a first electrical contact area on said first side and a
second electrical contact area on said second side;

an electrical component having a plurality of leads
electrically connected to said first electrical contact
area of said substrate; and

a capacitor plate electrically connected to said
second electrical contact area on said second side of said
substrate substantially opposite said first electrical
contact area of said substrate.

Claim 14 (Original): The assembled substrate of claim 13,
wherein said assembled substrate further comprises:

a first interposer between said component and said
first electrical contact area on said first side of said
substrate; and

a second interposer between said capacitor plate and
said second electrical contact area on said second side of
said substrate.

Claim 15 (previously presented): The assembled substrate of claim 14, wherein said first interposer and said second interposer are chosen from a group consisting of: a socket, or a conductive elastomeric material.

Claim 16 (previously presented): The assembled substrate of claim 13, wherein said substrate is chosen from a group consisting of: a PCB, an MCM, and a flexible substrate.

Claim 17 (previously presented): The assembled substrate of claim 13, wherein said component is chosen from a group consisting of: an LGA component, or a BGA component.

Claim 18 (Original): The assembled substrate of claim 13, wherein said capacitor plate has a plurality of layers of dielectric material separating a plurality of layers of conductive material.

Claim 19 (previously presented): The assembled substrate of claim 13, wherein said capacitor plate comprises:

a plurality of conductive power planes; and

a plurality of conductive ground planes, wherein said plurality of conductive power planes and said plurality of conductive ground planes are separated by one or more dielectric layers including a dielectric layer chosen from the materials comprising at least one of: FR4, a resin, an elastomeric material, or a ceramic.

Claim 20 (original): The assembled substrate of claim 13, wherein said capacitor plate is attached by solder to said second electrical contact area on said second side of said substrate.

Claims 21-29 (Canceled)